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(12) **United States Design Patent**  
**Ko et al.**

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(54) **LIGHT EMITTING DIODE PACKAGE**

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(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**  
CPC ... H01L 25/167; H01L 25/0753; H01L 33/08;  
H01L 33/10; H01L 33/20; H01L 33/38;  
H01L 33/52; H01L 33/54; H01L 33/60;  
H01L 33/62; H01L 33/382; H01L 33/486;  
H01L 33/642  
USPC ..... D13/180; D26/1; 257/79, 80, 81, 88,  
257/89, 95, 98, 99, 100, E33.058; 313/483,  
313/498, 500; 362/555, 800  
See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

D656,107 S *	3/2012	Hsu	.....	D13/180
D664,103 S *	7/2012	Sasaoka et al.	.....	D13/180
D664,104 S *	7/2012	Hsu	.....	D13/180
D664,105 S *	7/2012	Hsu	.....	D13/180
D664,107 S *	7/2012	Wang	.....	D13/180

D664,505 S *	7/2012	Ko	.....	D13/180
D664,510 S *	7/2012	Wang	.....	D13/180
D668,235 S *	10/2012	Chang et al.	.....	D13/180
D668,623 S *	10/2012	Hsu	.....	D13/180
D669,044 S *	10/2012	Hsu	.....	D13/180
D671,082 S *	11/2012	Chang	.....	D13/180
D678,225 S *	3/2013	Ko et al.	.....	D13/180
D678,226 S *	3/2013	Hsu et al.	.....	D13/180
D695,239 S *	12/2013	Ko et al.	.....	D13/180
D697,876 S *	1/2014	Hsu et al.	.....	D13/180
D697,877 S *	1/2014	Hsu et al.	.....	D13/180
2010/0102348 A1 *	4/2010	Lin	.....	257/98
2011/0127566 A1 *	6/2011	Yoon	.....	257/99
2012/0074451 A1 *	3/2012	Lin	.....	257/99
2012/0161180 A1 *	6/2012	Komatsu et al.	.....	257/98
2012/0211789 A1 *	8/2012	Lee et al.	.....	257/98

\* cited by examiner

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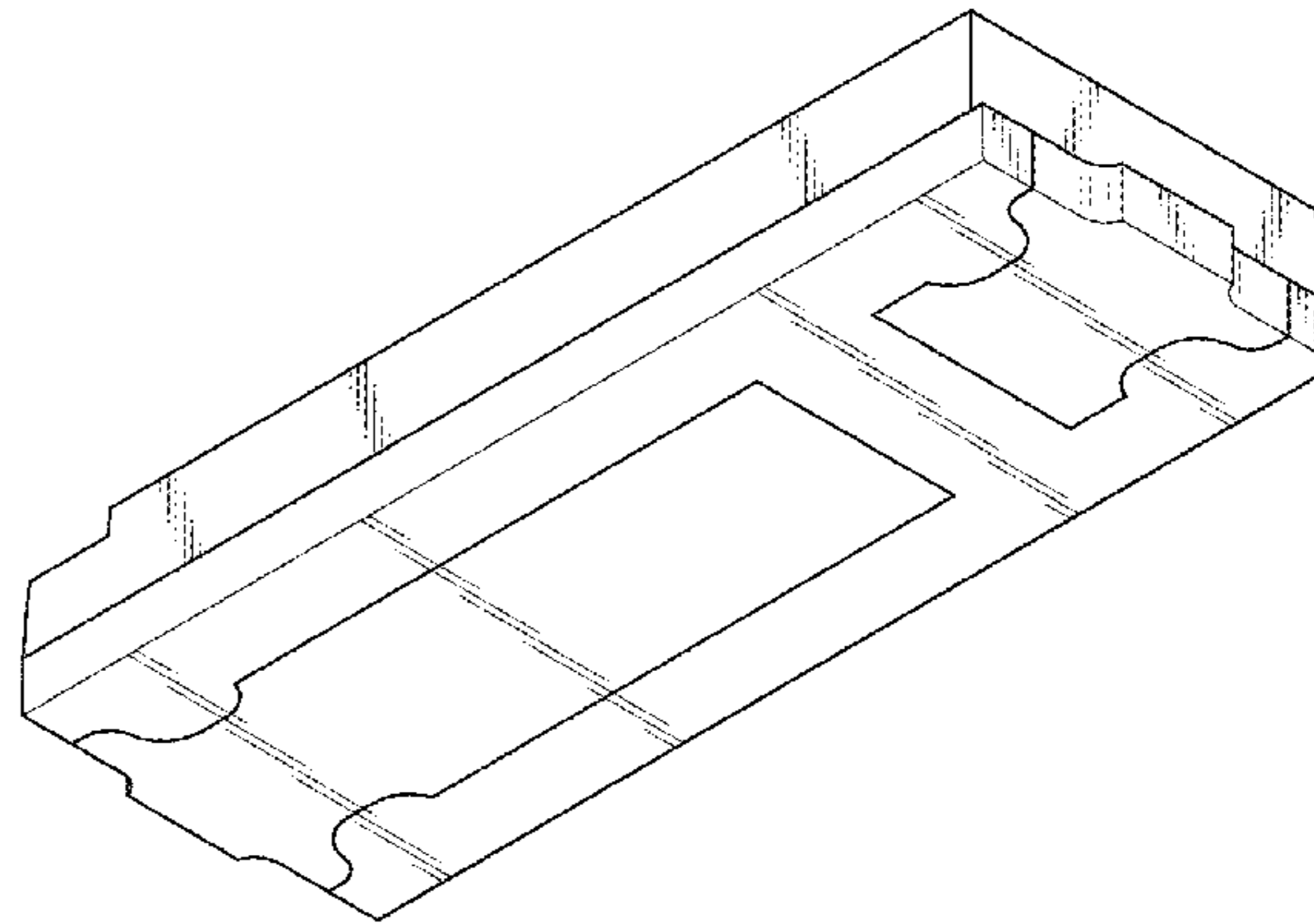
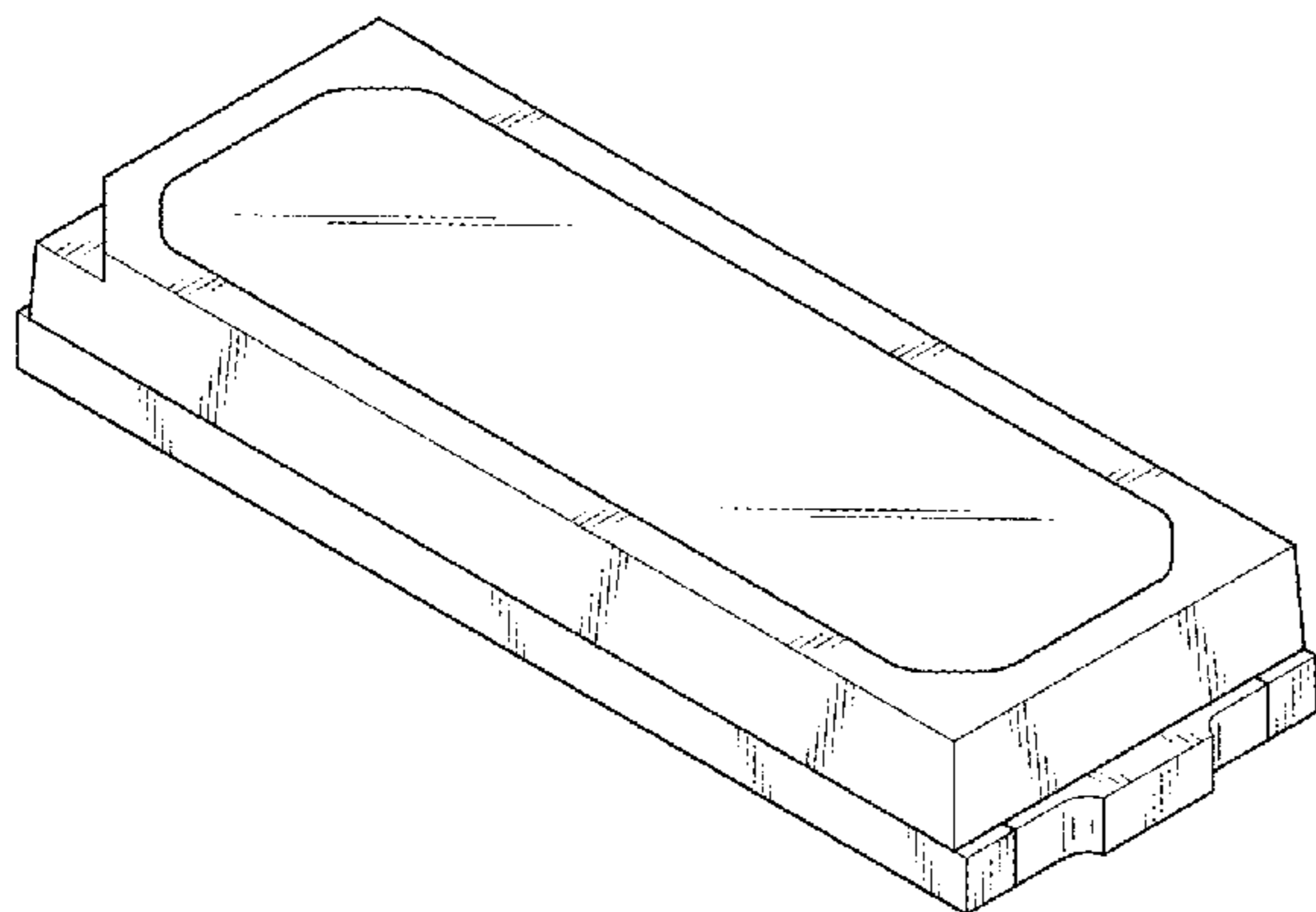
(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front perspective view of a light emitting diode package showing the new design;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a front elevational view thereof;  
FIG. 4 is a rear elevational view thereof;  
FIG. 5 is a left side elevational view thereof;  
FIG. 6 is a right side elevational view thereof;  
FIG. 7 is a top plan view thereof; and,  
FIG. 8 is a bottom plan view thereof.

**1 Claim, 8 Drawing Sheets**



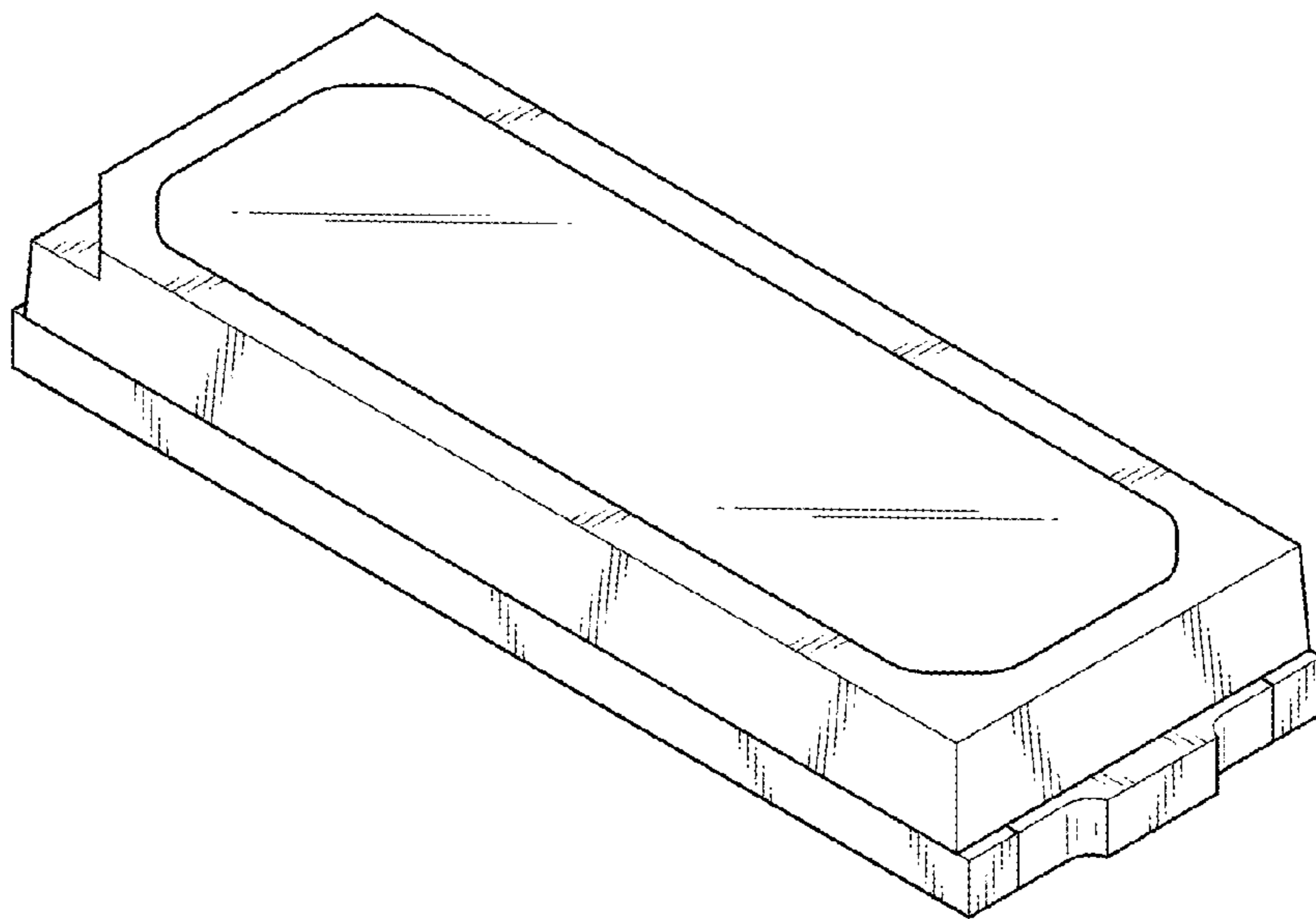


FIG. 1

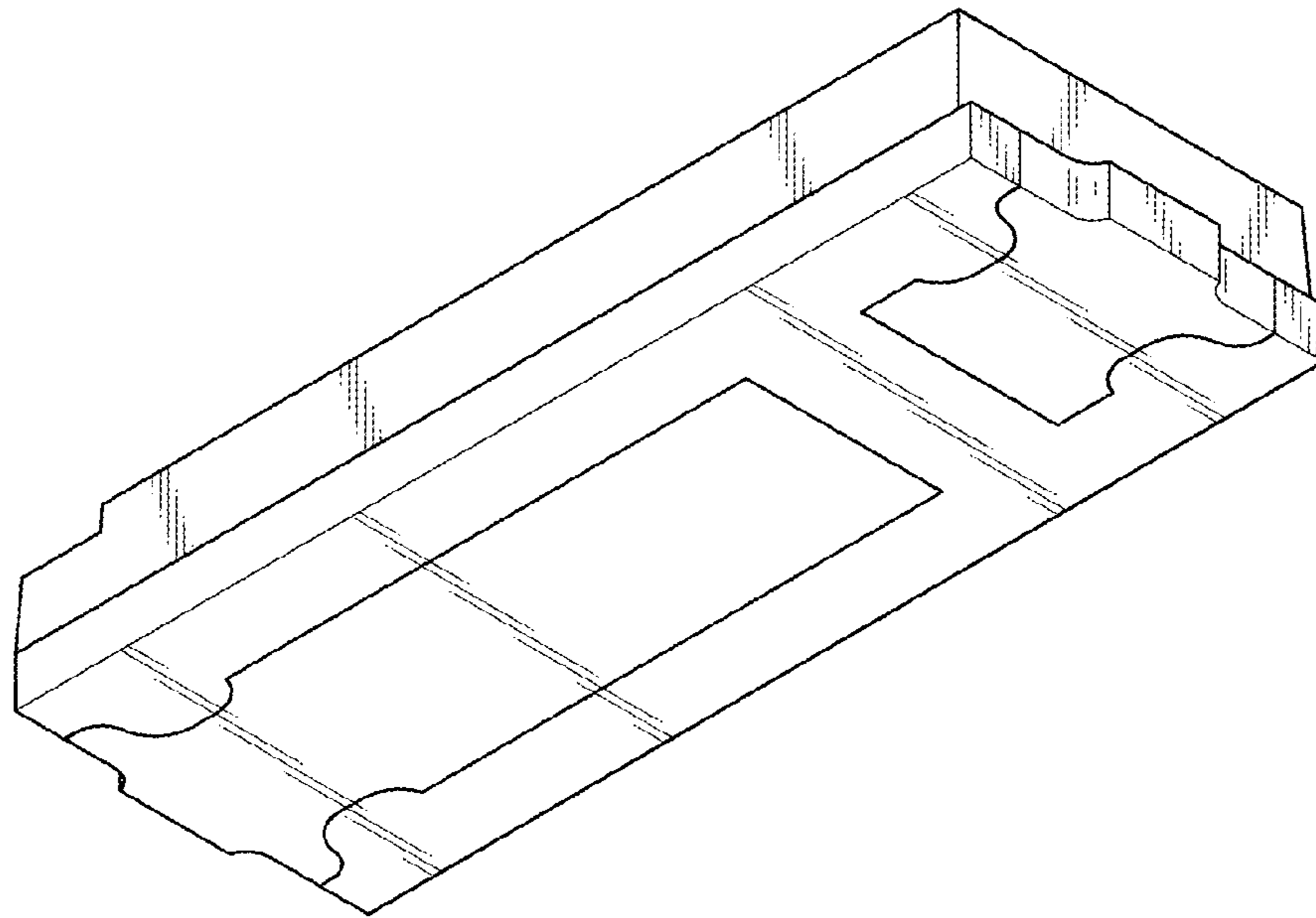


FIG.2

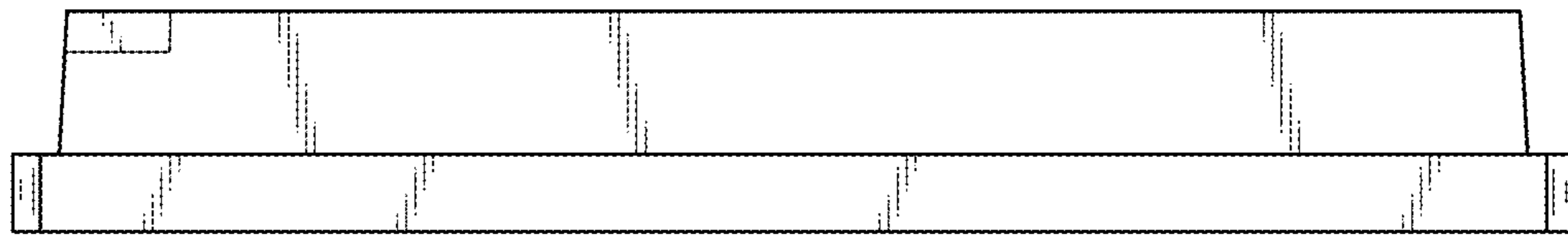


FIG.3

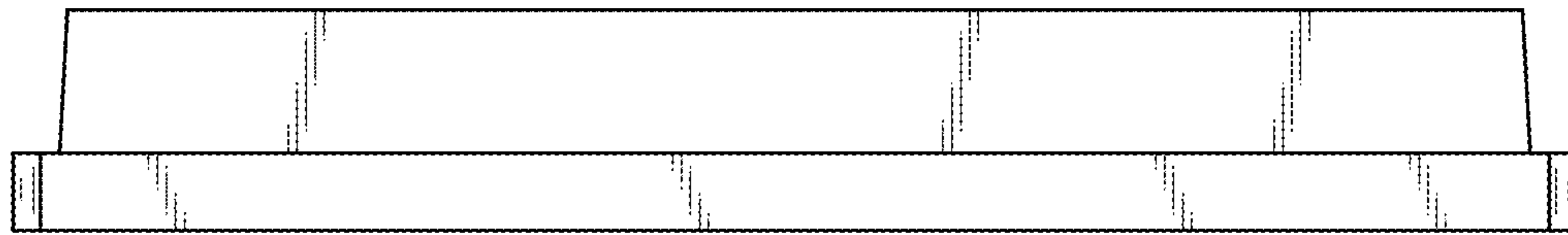


FIG.4

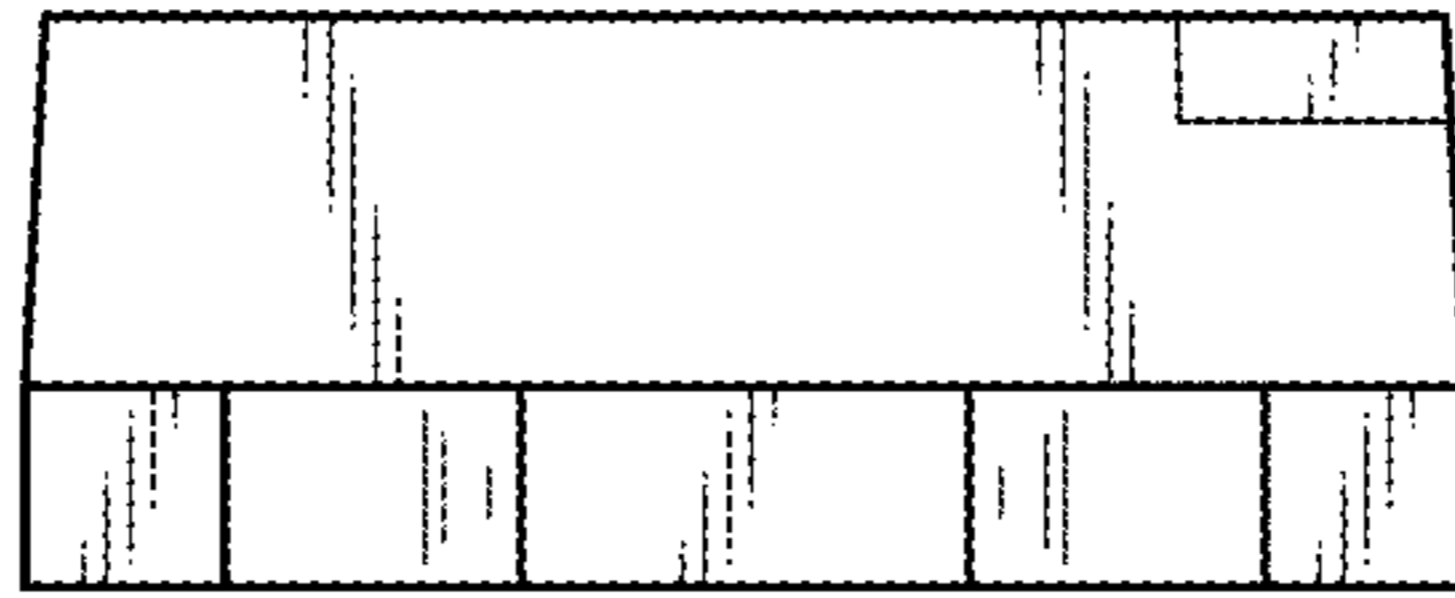


FIG.5

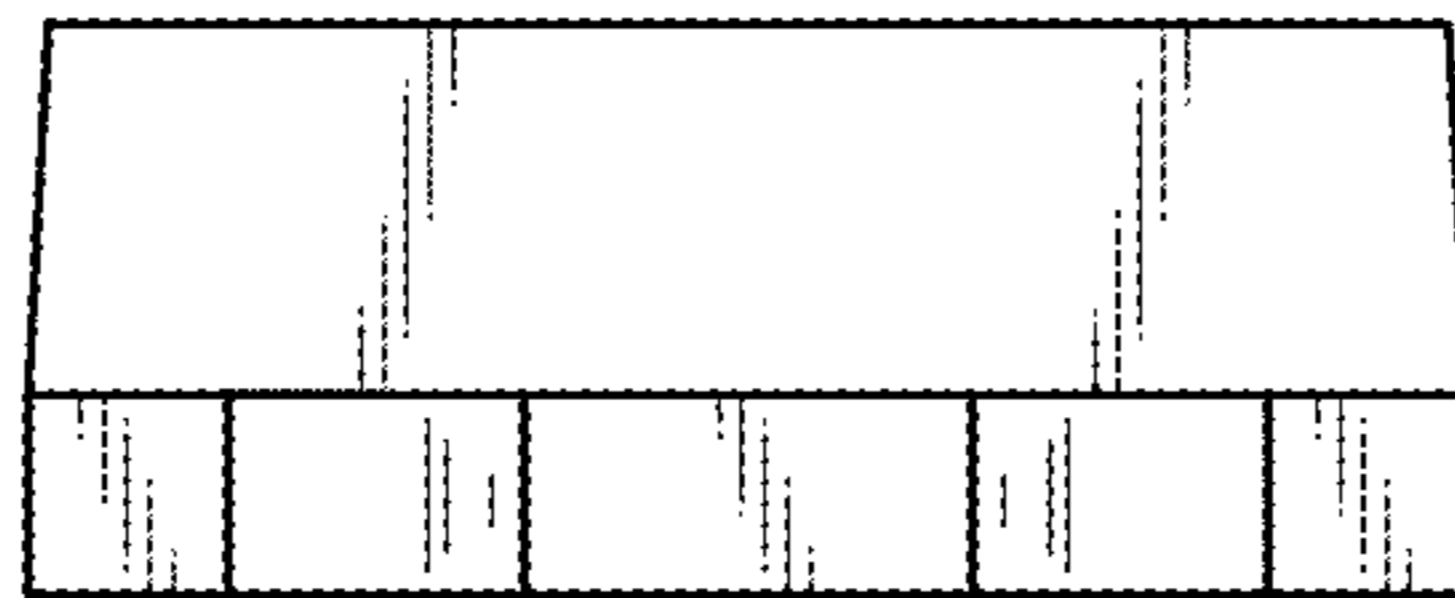


FIG.6

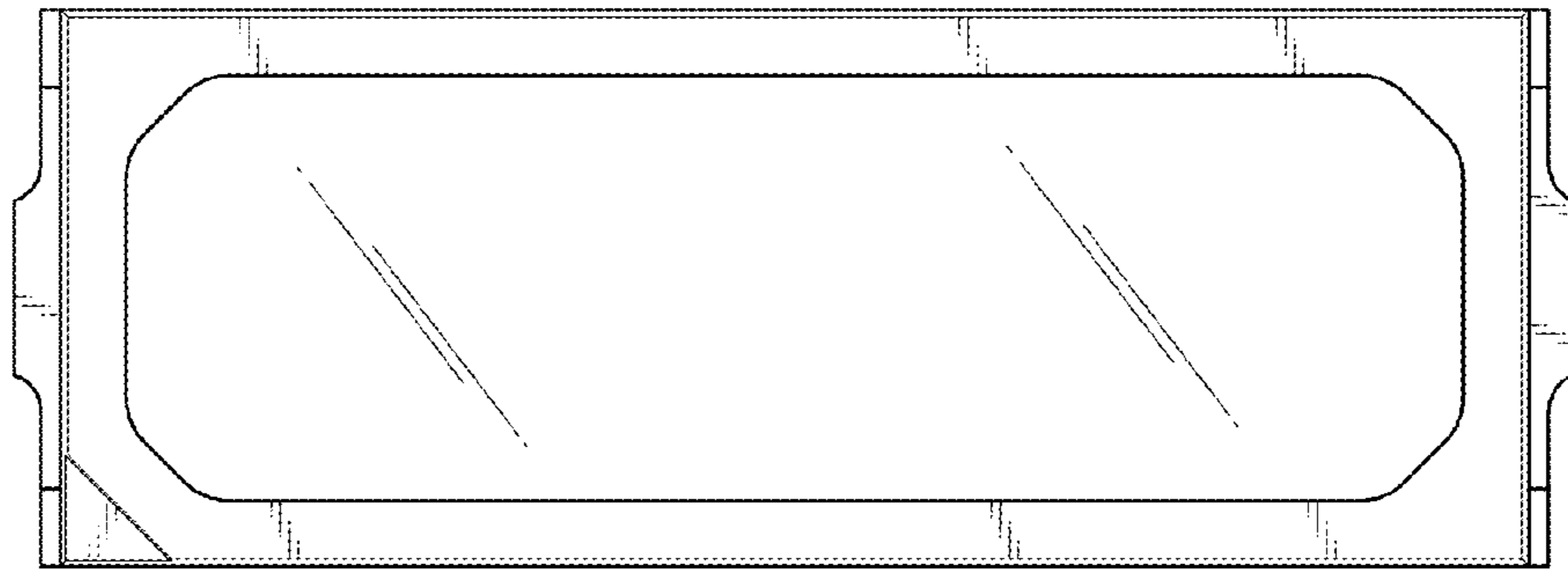


FIG.7



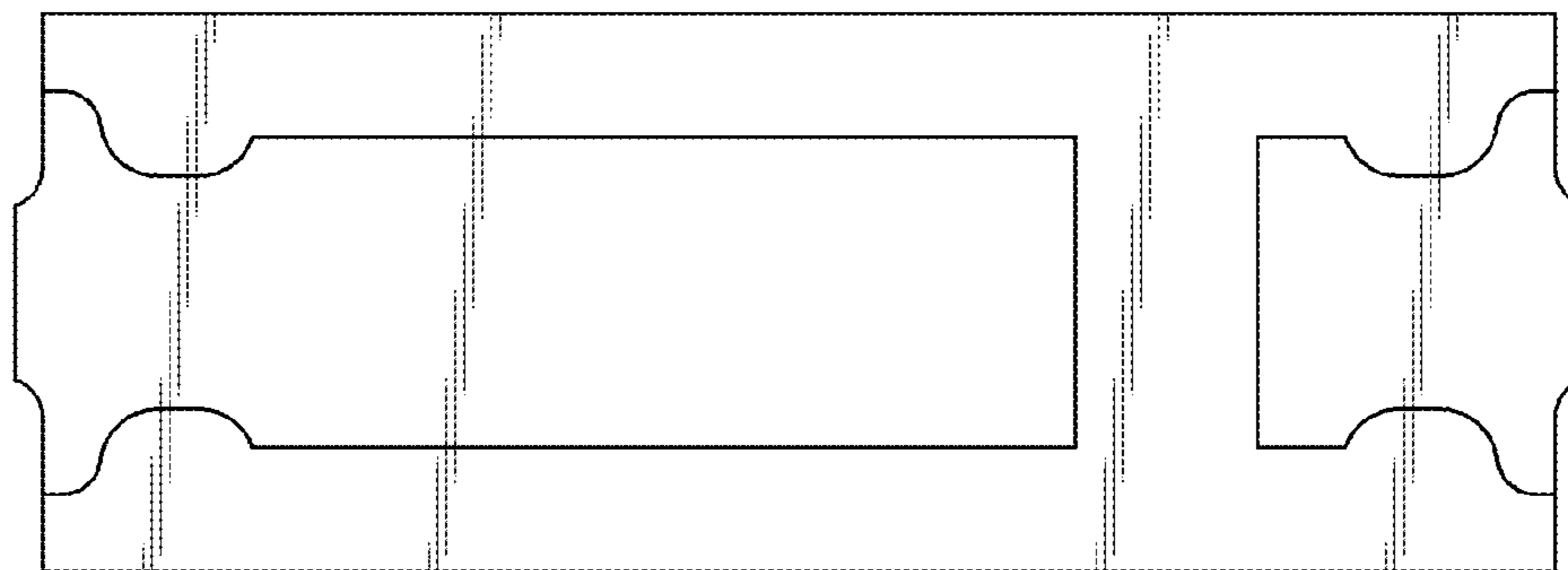


FIG. 8